Our flexible production system for diamond wire that supplies the wire for utilizing even collapsible or harder materials.

**Diamond wire**

**Material processing**  **Surface coating**

The wire, to which diamond abrasive grain electrodeposited, is to suit for wire saw machines of slicing collapsible or fragile wafers from silicon ingots for solar batteries, etc.

As a wire manufacturer, we are able to maximize utilization of our material processing technology, which is one of our strengths. We specialize in ultra-thin core wire with lower levels of cutting loss, mainly 70 micron diameter wire. We are realizing advances in thinning and high strength. Also, using our company’s uniquely developed production lines, we can provide flexible support even for the production of small quantities with a wide range of variety.

**Product features**

- As a wire manufacturer, we are able to achieve high levels of thinning and strength
- Various wire diameters and grain diameters are available
- The quality of evenness along the entire length of the wire is assured
- The amount of wire used while cutting has been reduced

**Product applications**

Wire saws for cutting solar batteries and semiconductor element wafers